

Data requirements for semiconductor die —

Part 5-2: Particular requirements and recommendations for die types — Bare die with added connection structures

ICS 31.080.01

National foreword

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Summary of pages

This document comprises a front cover, an inside front cover, the ES title page, pages 2 to 9, and a back cover.

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Amendments issued since publication

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English version

Data requirements for semiconductor die
Part 5-2: Particular requirements and recommendations for die types -
Bare die with added connection structures

This European Specification was approved by CENELEC on 2001-02-05.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

This European Specification has been prepared by the CENELEC BTTF 97-1, Known Good Die.

It was submitted to the vote during the meeting of BTTF 97-1 and approved by CENELEC as ES 59008-5-2 on 2001-02-05.

The following date was fixed:

- latest date by which the existence of the ES
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The structure of this European Specification is as follows:

ES 59008 Data requirements for semiconductor die

- Part 1 General requirements
- Part 2 Vocabulary
- Part 3 Mechanical, material and connectivity requirements
- Part 4 Specific requirements and recommendations
 - Part 4-1 Test and quality
 - Part 4-2 Handling and storage
 - Part 4-3 Thermal
 - Part 4-4 Electrical simulation
- Part 5 Particular requirements and recommendations for die types
 - Part 5-1 Bare die
 - Part 5-2 Bare die with added connection structures
 - Part 5-3 Minimally packaged die
- Part 6 Exchange data formats and data dictionary
 - Part 6-1 Data exchange - DDX
 - Part 6-2 Data dictionary